



The following material specifications are available:

Mark	Materials	Dimension	Surface qualities	Material No.
A	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	145547
B	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	145546
C	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Cu-Treatment on both sides (roughness-enhancement)	145553
A	Oxygenfree copper SE-Cu58 (C103)	0.018 x 250 mm	Plain – lamination quality (standard degreased)	145549
B	Oxygenfree copper SE-Cu58 (C103)	0.018 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	145550
D	High Tensile Copper CuMgAgP (ASTM: C15500)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	148050
E	High Tensile Copper CuMgAgP (ASTM: C15500)	0.010 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	148051
F	Nickel 99.6 (N201)	0.011 x 250 mm	Plain – lamination quality (standard degreased)	148380
G	Nickel 99.6 (N201)	0.011 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	148389

RELATED PRODUCTS

Please consider also our material for bipolar electrode application and tab ribbon:

- **Aluminum Copper-Clad material** used for tab ribbon and bipolar electrode application and
- **Tab Ribbon** made from Copper, Silver, Nickel and their alloys

For further information please visit our website: www.schlenk.com or contact our Area Sales Manager or your local representative. E-Mail contact: battery@schlenk.com